

04-17-2008

U.S. DEPARTMENT OF COMMERCE
United States Patent and Trademark Office



ET

103497354

To the Director of the U.S. Patent and Trademark Office, documents or the new address(es) below.

1. Name of conveying party(ies):

Kazuyuki Yamamoto (03/18/2008), Toshio
Mamiya (03/18/2008), Hidetoshi Kabasawa
(03/18/2008), Katsuhiko Yamada (03/19/2008)

Additional name(s) of conveying party(ies) attached? ☒ Yes ☐ No

3. Nature of conveyance/Execution Date(s):

Execution Date(s): in parentheses after inventor name

- ☒ Assignment ☐ Merger ☐ Change of Name
☐ Security Agreement ☐ Joint Research Agreement
☐ Government Interest Assignment
☐ Executive Order 9424, Confirmatory License
☐ Other

2. Name and address of receiving party(ies)

Name: Sony Corporation

Internal Address:

Street Address:

1-7-1 Konan, Minato-ku
Tokyo, 108-0075
JAPAN

City:

State:

Country: Zip:

Additional name(s) & address(es) attached: ☐ Yes ☒ No

4. Application or patent number(s):

A. Patent Application No.(s)

This application

☒ This document is being filed together with a new application.

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address to whom correspondence concerning document should be mailed:

Name: Randy J. Pritzker
WOLF, GREENFIELD & SACKS, P.C.

Internal Address:

Street Address: Federal Reserve Plaza
600 Atlantic Avenue

City: Boston

State: MA Zip: 02210-2206

Phone Number: 617.646.8000

Fax Number: 617.646.8646

Email Address: rpritzker@wolfgreenfield.com

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00

- ☐ Authorized to be charged by credit card
☐ Authorized to be charged to deposit account
☒ Enclosed
☐ None required (government interest not affecting title)

8. Payment Information

a. Credit Card Last 4 Numbers
Expiration Date

b. Deposit Account Number
Authorized User Name

9. Signature:

Randy J. Pritzker
Signature

April 9, 2008
Date

Randy J. Pritzker - 35,986
Name of Person Signing

Total number of pages including cover sheet, attachments, and documents:

8

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Dated: April 9, 2008

RECORDATION FORM COVER SHEET
(continued)

Additional Conveying Party(ies)/Execution Date(s) (1. Continued):

Takashi Yamada (03/17/2008), and Hideaki Kumagai (03/18/2008)

Additional Assignees (2. Continued):

Assignee Name: _____

Internal Address: _____

Street Address: _____

City: _____ State: _____ Country: _____ Zip: _____

Assignee Name: _____

Internal Address: _____

Street Address: _____

City: _____ State: _____ Country: _____ Zip: _____

Assignee Name: _____

Internal Address: _____

Street Address: _____

City: _____ State: _____ Country: _____ Zip: _____

Additional Applications and/or Patents (4. Continued):

Additional Patent Application Numbers

4A. Continued:

Additional Patent Numbers

4B. Continued:

Additional numbers attached?

☐ Yes☐ No

U.S. PTO
12/082174
04/09/2008

S08P0580US00
S1459.70452US00

Docket Number: _____

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in INFORMATION PROCESSING DEVICE AND DISK DRIVE DEVICE

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 1-7-1 Konan, Minato-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all prior rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date in this application in the spaces that follow: Serial Number: _____, Filing Date: _____.

This assignment executed on the dates indicated below.

Kazuyuki YAMAMOTO

Name of first or sole inventor

Kanagawa, Japan

Residence of first or sole inventor

Kazuyuki Yamamoto

Signature of first or sole inventor

March 18, 2008

Execution date of U.S. Patent Application

March 18, 2008

Date of this assignment

Toshio MAMIYA

March 18, 2008

Name of second inventor

Execution date of U.S. Patent Applicati

Tokyo, Japan

Residence of second inventor

March 18, 2008

Signature of second inventor

Date of this assignme

Hidetoshi KABASAWA

March 18, 2008

Name of third inventor

Execution date of U.S. Patent Applicati

Saitama, Japan

Residence of third inventor

March 18, 2008

Signature of third inventor

Date of this assignme

Katsuhiko YAMADA

March 19, 2008

Name of fourth inventor

Execution date of U.S. Patent Applicati

Tokyo, Japan

Residence of fourth inventor

March 19, 2008

Signature of fourth inventor

Date of this assignme

Takashi YAMADA

Name of fifth inventor

Execution date of U.S. Patent Applicati

Tokyo, Japan

Residence of fifth inventor

Signature of fifth inventor

Date of this assignme

U
Hideaki KUMAGAI

March 18, 2008

Name of sixth inventor

Execution date of U.S. Patent Applicati

Kanagawa, Japan

Residence of sixth inventor

Hideaki Kumagai

March 18, 2008

Signature of sixth inventor

Date of this assignme

Name of seventh inventor

Execution date of U.S. Patent Applicati

Residence of seventh inventor

Signature of seventh inventor

Date of this assignme

Name of eighth inventor

Execution date of U.S. Patent Applicati

Residence of eighth inventor

Signature of eighth inventor

Date of this assignme

Name of ninth inventor

Execution date of U.S. Patent Applicati

Residence of ninth inventor

Signature of ninth inventor

Date of this assignme

Docket Number: _____

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in
INFORMATION PROCESSING DEVICE AND DISK DRIVE DEVICE

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 1-7-1 Konan, Minato-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: _____, Filing Date: _____.

This assignment executed on the dates indicated below.

Kazuyuki YAMAMOTO

Name of first or sole inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of first or sole inventor

Signature of first or sole inventor

Date of this assignment

Toshio MAMIYA

Name of second inventor

Execution date of U.S. Patent Applica

Tokyo, Japan

Residence of second inventor

Signature of second inventor

Date of this assignm

Hidetoshi KABASAWA

Name of third inventor

Execution date of U.S. Patent Applica

Saitama, Japan

Residence of third inventor

Signature of third inventor

Date of this assignm

Katsuhiko YAMADA

Name of fourth inventor

Execution date of U.S. Patent Applica

Tokyo, Japan

Residence of fourth inventor

Signature of fourth inventor

Date of this assignm

Takashi YAMADA

Name of fifth inventor

17 Mar. 2008
Execution date of U.S. Patent Applica

Tokyo, Japan

Residence of fifth inventor

Takashi Yamada

Signature of fifth inventor

17 Mar. 2008
Date of this assignm

Hideaki KUMAGAI

Name of sixth inventor

Execution date of U.S. Patent Applicat

Kanagawa, Japan

Residence of sixth inventor

Signature of sixth inventor

Date of this assignm

Name of seventh inventor

Execution date of U.S. Patent Applicat

Residence of seventh inventor

Signature of seventh inventor

Date of this assignm

Name of eighth inventor

Execution date of U.S. Patent Applicat

Residence of eighth inventor

Signature of eighth inventor

Date of this assignm

Name of ninth inventor

Execution date of U.S. Patent Applicat

Residence of ninth inventor

Signature of ninth inventor

Date of this assignm